

Product/process change notification

PCN N° 2021-119-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Introduction of an additional assembly production and test site at Hana Semiconductor (Ayutthaya, Thailand) Co., Ltd. for products 1ED44176N01F and 2ED28073J06F.

Introduction of a new leadframe and mold compound for products IRS2302SPBF and IRS2302STRPBF with no change of assembly production and test sites

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2022-12-16**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress. We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance. For further details, please visit our website: <https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Management Board Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg

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► **Products affected**

Please refer to attached affected product list
 “PCN_2021-119-A_[customer-no].pdf”

► **Detailed change information**

Subject Introduction of an additional assembly production and test site at Hana Semiconductor (Ayutthaya, Thailand) Co., Ltd. for products 1ED44176N01F and 2ED28073J06F.
 Introduction of a new leadframe and mold compound for products IRS2302SPBF and IRS2302STRPBF with no change of assembly production and test sites.

Reason Expansion of production capacity to ensure continuity of supply and enable flexible manufacturing as well as harmonizing material due to Hana Semiconductor’s manufacturing strategy.

Description

<u>Old</u>	<u>New</u>
<u>1ED44176N01F</u> ■ JCET Group (Suzhou-Suqian, Jiangsu) Co., Ltd. ■ Carsem Sdn.Bhd.(Malaysia)	<u>1ED44176N01F</u> ■ JCET Group (Suzhou-Suqian, Jiangsu) Co., Ltd ■ Carsem Sdn.Bhd.(Malaysia) ■ Hana Semiconductor (Ayutthaya, Thailand) Co., Ltd.
<u>2ED28073J06F</u> ■ JCET Group (Suzhou-Suqian, Jiangsu) Co., Ltd	<u>2ED28073J06F</u> ■ JCET Group (Suzhou-Suqian, Jiangsu) Co., Ltd ■ Hana Semiconductor (Ayutthaya, Thailand) Co., Ltd.
<u>IRS2302SPBF and IRS2302STRPBF</u> ■ Leadframe: High Density Leadframe ■ Wire: Au ■ Mold compound: CEL9220HF	<u>IRS2302SPBF and IRS2302STRPBF</u> ■ Leadframe: Ultra High Density Leadframe ■ Wire: Cu ■ Mold compound: CEL8240HF

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- ▶ **Product identification** Ensured by internal traceability in manufacturing execution systems.

- ▶ **Impact of change** Based on the qualification performed, Infineon does not see any negative impact on quality, function or reliability. No change in fit, form and function.

- ▶ **Attachments** PCN_2019-119-A_[customer-no].pdf affected product list

- ▶ **Time schedule**
 - Final qualification report On request
 - First samples available On request
 - Intended start of delivery 2022-11-30 or earlier on customer request.

If you have any questions, please do not hesitate to contact your local sales office.

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Affected products sold to FUTURE ELECTRONICS INC. (4000624)

Sales name	SP number	OPN	Package	Customer part number
IRS2302STRPBF	SP001548874	IRS2302STRPBF	SOIC 8N	IRS2302STRPBF